• Supplementary File •

Solid-state nonvolatile memories based on vdW heterostructure-based vertical-transport ferroelectric field-effect transistors

Qiyu YANG^{1,2}, Zheng-Dong LUO^{1,2*}, Fei XIAO¹, Junpeng ZHANG³, Dawei ZHANG^{4,5}, Dongxin TAN², Xuetao GAN^{6*}, Yan LIU^{1,2}, Zhufei CHU⁷, Yinshui XIA⁷ & Genquan HAN^{1,2}

¹Hangzhou Institute of Technology, Xidian University, Hangzhou 311200, China;

²State Key Discipline Laboratory of Wide Band Gap Semiconductor Technology, School of Microelectronics,

Xidian University, Xi'an 710071, China;

³School of Artificial Intelligence, Xidian University, Xi'an 710071, China;

⁴School of Materials Science and Engineering, UNSW Sydney, Sydney NSW 2052, Australia;

⁵ARC Centre of Excellence in Future Low-Energy Electronics Technologies (FLEET), UNSW Sydney, Sydney NSW 2052, Australia;

⁶Key Laboratory of Light Field Manipulation and Information Acquisition, Ministry of Industry and Information Technology,

and Shaanxi Key Laboratory of Optical Information Technology, School of Physical Science and Technology,

Northwestern Polytechnical University, Xi'an 710129, China;

⁷Faculty of Electrical Engineering and Computer Science, Ningbo University, Ningbo 315211, China

1 Supplementary note 1: Fabrication process for the VT-FeFET

The graphene, MoS_2 and $MoTe_2$ flakes were mechanically exfoliated onto polydimethylsiloxane (PDMS, Gel-Pak@) stamps using the Scotch tape method. The graphene flakes were transferred via PDMS stamps onto the 285 nm SiO₂/Si substrates. And then the MoTe₂ and MoS₂ flakes were transferred onto the graphene flakes of interest to form the $MoS_2/MoTe_2/graphene$ heterostructures by dry transfer method using a location-precise transfer platform. After each transfer step, the sample was annealed at 200 °C in vacuum for 1 h to remove polymer residue. Au electrodes pre-defined by photolithography on Si substrate were transferred using PDMS onto the 2D flakes to form the source contact on MoS₂ and contact on graphene. The as-fabricated VT-FETs were annealed at 200 °C in vacuum for 2 h to improve the contact between the transferred metal electrodes and 2D materials. Next, two-layer P(VDF-TrFE) (70:30 in mol%) thin films (~100 nm in thickness) as gate dielectric layer were spin coated to the sample for two times, followed by an annealing at 135 °C in vacuum for 6 h. Au metal stripes were transferred onto the vertical channel by dry transfer method, and the Au/P(VDF-TrFE)/MoS₂/MoTe₂/graphene structures were finally annealed at 120°C in vacuum for 1 h.

^{*} Corresponding author (email: zhdluo@xidian.edu.cn, xuetaogan@nwpu.edu.cn)



 $\label{eq:Figure 1} {\bf Figure 1} \quad {\rm The \ optical \ image \ of \ fabrication \ process \ for \ the \ VT-FeFETs}.$



2 Supplementary note 2: P-V hysteresis loop of P(VDF-TrFE) capacitor

Figure 2 Ferroelectric hysteresis loop of Au/P(VDF-TrFE) (100 nm)/Si capacitor. (a) Ferroelectric hysteresis loop and polarization switching current measured at 100 Hz. (b) A set of ferroelectric minor loops measured at different sweeping voltage at 100 Hz. The ferroelectric minor loops indicate that P(VDF-TrFE) films can exhibit multiple polarization levels, which is the physical origin for the realization of memristive switching in P(VDF-TrFE) based VT-FeFET.

3 Supplementary note 3: Transfer characteristics at different memory states for VT-FeFETs

As the ferroelectric P(VDF-TrFE) thin film is biased in the linear dielectric regime, the VT-FeFETs show an electrostatic doping effect that is the same as the conventional linear dielectrics. As shown in Fig. S3a, the Vth with the memory states, which is generated from the polarization orientation. As the ferroelectric P(VDF-TrFE) gate is biased in the linear dielectric regime, e.g. the VT-FeFET operates in a regular FET mode, the repeatedly measured transfer curves remain a stable $V_{\rm th}$ for up to 20 cycles.



Figure 3 Transfer curves of the $P(VDF-TrFE)/MoS_2/MoTe_2$ VT-FeFET (a) Transfer curves under different memory states. (b) Vg sweeping cycle at regular FET mode.

4 Supplementary note 4: Calculation of nonlinearity in weight updating process

An ideal weight update characteristic of synapse should be linearly proportional to the number of programming voltage pulses. However, realistic devices reported in the literatures do not follow this ideal curve, and the conductance typically changes rapidly at the beginning of LTP and LTD and then gradually saturates. We have adopted a device behaviour model [1] to capture the nonlinear weight update behaviour, where the variation of conductance with the number of pulses (P) is described by the following formulas:

$$G_P = B(1 - e^{-P/A}) + G_{min}$$
(1)

$$G_D = -B(1 - e^{P - P_{max}/A}) + G_{max}$$
(2)

$$B = (G_{max} - G_{min})(1 - e^{-P_{max}/A})$$
(3)

$$\alpha = 1.726/(A + 0.162) \tag{4}$$

Here, G_P and G_D are conductance of LTP and LTD. G_{max} represents the maximum conductance value, G_{min} is the minimum conductance value and P_{max} is the maximum pulse number to switch between the maximum and minimum conductance states, which are all extracted from the experimental data. A is a parameter that controls the nonlinear behaviour of weight updates, which can be positive or negative. B is a function of A which fits the range of memristive switching. The nonlinear parameter A is obtained by fitting the curve with LTP and LTD. α is a parameter describing the nonlinearity of weight update. The higher α is, the more nonlinear the curve is. [2]

5 Supplementary note 5: Current density for the VT-FeFET



Figure 4 Current density of VT-FeFET. (a) Illustration of the $MoS_2/MoTe_2$ overlapping area. The heterojunction region is highlighted in red. (b) Transfer curve of VT-FeFET. The vertical axis represents drain current (a) Current density calculated form transfer curve in (b).



6 Supplementary note 6: Operation mechanism for VTFETs

Figure 5 Band profiles of the $MoS_2/MoTe_2$ VTFET under different conditions. (a) Band diagram of $MoS_2/MoTe_2$ heterojunction before contact. (b) Band diagram of the $MoS_2/MoTe_2$ heterojunction under different applied gate and drain voltage.

7 Supplementary note 7: Benchmark the device performance metrics of 2D FeFETs

Table 1 Benchmark of the device performance metrics of 2D FeFETs				
Structure	Material	On/Off ratio	Conductance states	Endurance (cycles)
MFS LT-FeFET [3]	PZT/WS_2	NA	10	NA
MFS LT-FeFET [4]	$pSi/HZO/MoS_2$	10^{5}	40	NA
MFS LT-FeFET [5]	$pSi/HZO/SnS_2$	10^{6}	64	1.4×10^{4}
MFS LT-FeFET [6]	$\rm Au/Ni/CuInP_2S_6/MoS_2$	$> 10^{3}$	NA	NA
Dual-gate MFS LT-FeFET [7]	$Au/P(VDF-TrFE)/MoS_2$	10^{5}	100	NA
MFIS LT-FeFET [8]	$Au/CuInP_2S_6/hBN/InSe$	$> 10^{4}$	NA	1×10^{3}
MFIS LT-FeFET [9]	${\rm Gate}/{\rm CuInP_2S_6}/{\rm hBN}/{\rm ReS_2}$	104	25	NA
MFIS LT-FeFET [10]	$\rm Au/CuInP_2S_6/hBN/WSe_2$	10^{4}	NA	NA
MFMIS LT-FeFET [11]	$\rm W/HZO/W/Al_2O_3/MoS_2$	10^{7}	64	5×10^{4}
MFMIS LT-FeFET [12]	$\rm CuInP_2S_6/Gr/hBN/Te$	10^{3}	NA	NA
Ferroelectric semiconductor [13] channel LT-FeFET	Au/hBN/3R $MoS_2/Graphene$	10^{6}	NA	1×10^{4}
Ferroelectric semiconductor [14] channel LT-FeFET	${\rm Au/hBN}/\alpha$ - ${\rm In_2Se_3}$	10^{3}	30	500
Ferroelectric semiconductor [15] channel LT-FeFET	$\mathrm{pSi/HfO_2/\alpha}-\mathrm{In_2Se_3}$ $\mathrm{pSi/SiO_2/\alpha}-\mathrm{In_2Se_3}$	10 ⁸	NA	NA
Vertical channel MFS VT-FeFET (This work)	$\rm Au/P(VDF\text{-}TrFE)/\ MoS_2/MoTe_2/Gr$	$> 10^{4}$	16	1×10^3

References

- 1 Chen P Y, Peng X and Yu S, NeuroSim+: An integrated device-to-algorithm framework for benchmarking synaptic devices and array architectures. In: Proceedings of IEEE International Electron Devices Meeting (IEDM), San Francisco, CA, USA, 2017, 6.1.1-6.1.4
- 2 Yu S, Neuro-inspired computing with emerging nonvolatile memorys. In: Proceedings of the IEEE, 2018, 106(2): 260-285
- 3 Luo Z D, Xia X, Yang M M, Wilson N R, Gruverman A, Alexe M, Artificial optoelectronic synapses based on ferroelectric field-effect enabled 2D transition metal dichalcogenide memristive transistors. ACS Nano, 2020, 14(1), 746–754
- 4 Jeon H, Kim S G, Park J, Kim S H, Park E, Kim J, Yu H Y, Hysteresis modulation on van der Waals-based ferroelectric field-effect transistor by interfacial passivation technique and its application in optic neural networks. Small, 2020, 16(49), 1–8
- 5 Song C M, Kim D, Lee S, Kwon H J, Ferroelectric 2D SnS2 analog synaptic FET. Advanced Science, 2024, 2308588, 1–7
- 6 Si M, Liao P Y, Qiu G, Duan Y, Ye P D, Ferroelectric field-effect transistors based on MoS2 and CuInP2S6 two-dimensional van der Waals heterostructure. ACS Nano, 2018, 12(7), 6700–6705
- 7 Luo Z D, Zhang S, Liu Y, Zhang D, Gan X, Seidel J, Liu Y, Han G, Alexe M, Hao Y, Dual-ferroelectric-coupling-engineered two-dimensional transistors for multifunctional in-memory computing. ACS Nano, 2022 16(2), 3362–3372
- 8 Singh P, Baek S, Yoo H H, Niu J, Park J H, Lee S, Two-dimensional CIPS-InSe van der Waal heterostructure ferroelectric field effect transistor for nonvolatile memory applications. ACS Nano, 2022, 16(4), 5418–5426
- 9 Soliman M, Maity K, Gloppe A, Mahmoudi A, Ouerghi A, Doudin B, Kundys B, Dayen J F, Photoferroelectric all-van-der-Waals heterostructure for multimode neuromorphic ferroelectric transistors. ACS Applied Materials and Interfaces, 2023, 15(12), 15732–15744
- 10 Ram A, Maity K, Marchand C, Mahmoudi A, Kshirsagar A R, Soliman M, Taniguchi T, Watanabe K, Doudin B, Ouerghi A, Reichardt S, O'Connor I, Dayen J F, Reconfigurable multifunctional van der Waals ferroelectric devices and logic circuits. ACS Nano, 2023, 17(21), 21865–21877
- 11 Xiang H, Chien Y C, Li L, Zheng H, Li S, Duong N T, Shi Y, Ang K W, Enhancing memory window efficiency of ferroelectric transistor for neuromorphic computing via two-dimensional materials integration. Advanced Functional Materials, 2023, 33(42), 1–10
- 12 Yang F, Ng H K, Ju X, Cai W, Cao J, Chi D, Suwardi A, Hu G, Ni Z, Wang X R, Lu J, Wu J, Emerging opportunities for ferroelectric field-effect transistors: integration of 2D materials. Advanced Functional Materials, 2024, 2310438, 1–23
- 13 Yang T H, Liang B W, Hu H C, Lan Y W, et.al., Ferroelectric transistors based on shear-transformation-mediated rhombohedral-stacked molybdenum disulfide. Nature Electronics, 2024, 7(1), 29–38
- 14 Wang S, Liu L, Gan L, Chen H, Hou X, Ding Y, Ma S, Zhang D W, Zhou P, Two-dimensional ferroelectric channel transistors integrating ultra-fast memory and neural computing. Nature Communications, 2021, 12(1), 1–9
- 15 Si M, Saha A K, Gao S, Qiu G, Qin J, Duan Y, Jian J, Niu C, Wang H, Wu W, Gupta S K, Ye P D, A ferroelectric semiconductor field-effect transistor. Nature Electronics, 2019, 2(12), 580–586